

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of
PENDSE et al.

Application No.: 09/802,664

Filed: March 9, 2001

Title: **Flip chip interconnection
structure**

Examiner: Leonardo Andujar

Group Art Unit: 2826

Date: June 28, 2002

Certificate of Mailing

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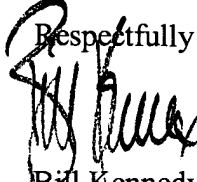
Dear Sir:

In response to the Office Action mailed May 31, 2002 (Restriction Requirement),
enclosed please find:

- [X] Preliminary Amendment and Response to Restriction Requirement;
- [X] Information Disclosure Statement (in duplicate);
- [X] PTO-1449 (PTO/SB/08A) form and copies of twenty (20) cited references.

The Commissioner is hereby authorized to charge any additional fees that may be required by this paper, and to credit any overpayment, to Deposit Account No. 50-0869 (Docket No. CPAC 1003-1US). A duplicate of this paper is enclosed.

Respectfully submitted,



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Date: June 28, 2002

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) Examiner: Leonardo Andujar

) Group Art Unit: 2826

) Date: June 28, 2002

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Linda Shaw

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Dear Sir:

PRELIMINARY AMENDMENT

In the claims:

Please amend claims 12 - 17 as shown in the attached "Attachment under Rule 1.121", as follows:

12. The flip chip interconnection structure of claim 10 wherein the deformable material of the first member comprises gold.

13. The flip chip interconnection structure of claim 10 wherein the second member comprises a surface pad.

14. The flip chip interconnection structure of claim 10 wherein the second member comprises a lead.